

RESPONSE TO NOTICE OF NON-COMPLIANCE
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CLAIMS

1. (Previously Amended) A thermal transfer device comprising a thermal source maintained in parallel to a thermal sink and having a thermally conductive, compressible, multiple turn coil between the thermal source and the thermal sink.
2. (Previously Amended) The thermal transfer device according to claim 1 wherein the thermal sink surrounds the thermal source.
3. (Previously Amended) The thermal transfer device according to claim 1 wherein said thermal source is made of a dielectric material.
4. (Previously Amended) The thermal transfer device according to claim 1 wherein said thermal source is made of sapphire.
5. (Previously Amended) The thermal transfer device according to claim 1 wherein said thermal sink is made of a dielectric material.
6. (Previously Amended) The thermal transfer device according to claim 1 wherein said thermally conductive coil is made of copper.
7. (Previously Amended) The thermal transfer device according to claim 6 wherein said copper coil is made from copper wire about 0.011 inch thick.
8. (Previously Amended) The thermal transfer device according to claim 1 wherein the thermal source and the thermal sink are concentric.
9. (Previously Amended) The thermal transfer device according to claim 8 wherein a surface of the thermal sink facing the thermal source is grooved to accommodate the compressible coil.

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10. (Previously Amended) The thermal transfer device according to claim 2 wherein the thermal sink includes a means of cooling.

11. (Previously Amended) The thermal transfer device according to claim 1 wherein the conductive, compressible, multiple turn coil fills a space between the thermal source and the thermal sink.

12. (Previously Amended) In a vacuum chamber comprising a processing chamber including a substrate to be processed, and a processing gas inlet source that traverses a microwave energy source for forming a plasma from a processing gas, the improvement comprising:

a microwave impervious gas inlet made of a dielectric material in the form of a tube that provides a thermal source, the dielectric tube surrounded by a concentric dielectric tube that provides a thermal sink, and a compressible, conductive multiple turn coil between the thermal source and the thermal sink.

13. (Previously Amended) The vacuum chamber according to claim 12 wherein said coil is made of copper.

14. (Previously Amended) The vacuum chamber according to claim 12 wherein said gas inlet source is made of sapphire.